

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(electrode\$1 near (potential voltage)) with (chip die) with (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/12 09:29
L2	13	(electrode\$1 near (potential voltage)) with (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/12 09:40
L3	1839	(first near chip) and stack\$3 and (second near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/12 09:39
L4	10	3 and (electrode\$1 near (potential voltage))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/12 09:54
L5	115	3 and (electrode\$1 with (potential voltage))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/12 09:54
S1	3632	257/777,778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/12 09:27
S2	232	S1 and (((first upper lower) near chip) with ((second lower upper) near chip) with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 17:54
S3	11	S1 and (((first upper lower) near chip near2 (first near substrate)) with ((second lower upper) near chip near2 (second near substrate)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 17:51

S4	11	S1 and (((first near chip) near2 (first near substrate)) with ((second near chip) near2 (second near substrate)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 17:53
S5	731289	"257"/\$.ccls. "438"/\$.ccls. "361"/\$.ccls. "29"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 17:52
S6	32	S5 and (((first near chip) near2 (first near substrate)) with ((second near chip) near2 (second near substrate)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 17:53
S7	497	S5 and ((first near chip) with (second near chip) with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 17:57
S8	125	S7 and ((first near substrate) with (second near substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 17:55
S9	27	S8 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:00
S10	35	S5 and ((first near chip) with (second near chip) with (wir\$3 near substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:05
S11	401	S1 and ((first near chip) with (second near chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:00
S12	60	S11 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:07

S13	38	((first near chip) with (second near chip) with (wir\$3 near substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:07
S14	361	(first near chip) with stack\$3 with (second near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:17
S15	37	S14 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:17
S16	1831	(first near chip) and stack\$3 and (second near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:29
S17	195	S16 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:30
S18	231	((lower bottom) near chip) with stack\$3 with ((top upper) near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:31
S19	43	S18 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:32
S20	792	((lower bottom) near chip) and stack\$3 and ((top upper) near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:31
S21	96	S20 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:42

S22	26661	flip near chip\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:41
S23	489	S22 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:43
S24	86	S23 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:43
S25	229	S22 and S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:43
S26	50	S25 and (wir\$3 near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/11 18:43